



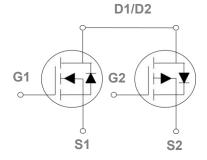
Product data sheet

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TO252-4 Pin Configuration





Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications

Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

BVDSS	RDSON	ID
40V	19m Ω	15A
-40V	$38 m\Omega$	-12A

Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Symbol Parameter Rating		Units	
V _{DS}	Drain-Source Voltage	40	-40	V
V _{GS}	Gate-Source Voltage	±20	±20	V
	Drain Current – Continuous (T _C =25°C)	15	-12	A
ID	Drain Current – Continuous (T _C =100°C)	9	-7	A
I _{DM}	Drain Current – Pulsed ¹	60	-48	A
D	Power Dissipation (T _c =25°C)	20)	W
PD	Power Dissipation – Derate above 25°C	0.1	6	W/°C
T _{STG}	Storage Temperature Range	-55 to	-55 to 150	
TJ	Operating Junction Temperature Range	-55 to	-55 to 150	

Thermal Characteristics

Symbol	Symbol Parameter		Max.	Unit
R _{θJC}	Thermal Resistance Junction to Case		6	°C/W
R _{0JA}	Thermal Resistance Junction to Ambient		62	°C/W





N-CH Electrical Characteristics (T_J=25 °C, unless otherwise)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
0BV _{DSS} /0T _J	BV _{DSS} Temperature Coefficient	Reference to 25° C , I _D =1mA		0.04		V/°C
	Drain Source Lookage Current	$V_{\text{DS}}\text{=}40V$, $V_{\text{GS}}\text{=}0V$, $T_{\text{J}}\text{=}25^{\circ}\text{C}$			1	uA
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}32\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}125^{\circ}\text{C}$			10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Б	R _{DS(ON)} Static Drain-Source On-Resistance	V _{GS} =10V , I _D =6A		19	30	mΩ
NDS(ON)		V _{GS} =4.5V , I _D =4A		30	42	mΩ
V _{GS(th)}	Gate Threshold Voltage	-V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
OV _{GS(th)}	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID -2500A		-3		mV/°C
gfs	Forward Transconductance	V _{DS} =10V , I _D =3A		6.5		S

Dynamic and switching Characteristics

Qg	Total Gate Charge ^{2,3}		 5.2	
Q _{gs}	Gate-Source Charge ^{2,3}	$V_{\text{DS}}\text{=}20V$, $V_{\text{GS}}\text{=}4.5V$, $I_{\text{D}}\text{=}6A$	 1.2	nC
Q _{gd}	Gate-Drain Charge ^{2 , 3}		 2.5	
T _{d(on)}	Turn-On Delay Time ^{2 , 3}		 3.2	
Tr	Rise Time ^{2 , 3}	$V_{DD}\texttt{=}\texttt{2}0V$, $V_{GS}\texttt{=}\texttt{4}.5V$, $R_{G}\texttt{=}\texttt{2}5\Omega$	 8.6	20
T _{d(off)}	Turn-Off Delay Time ^{2 , 3}	I _D =1A	 18	ns
T _f	Fall Time ^{2 , 3}		 6	
C _{iss}	Input Capacitance		 420	
C _{oss}	Output Capacitance	V_{DS} =15V , V_{GS} =0V , F=1MHz	 65	pF
C _{rss}	Reverse Transfer Capacitance		 40	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current				15	А
I _{SM}	Pulsed Source Current	V _G =V _D =0V , Force Current			30	А
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

2. The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%.$

3. Essentially independent of operating temperature.





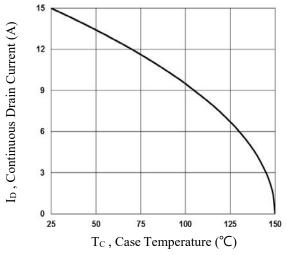
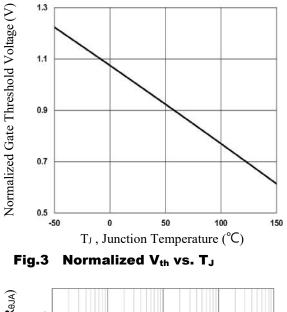
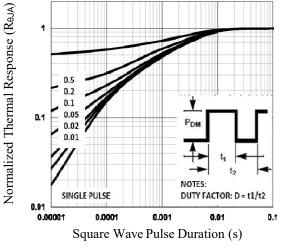


Fig.1 Continuous Drain Current vs. Tc







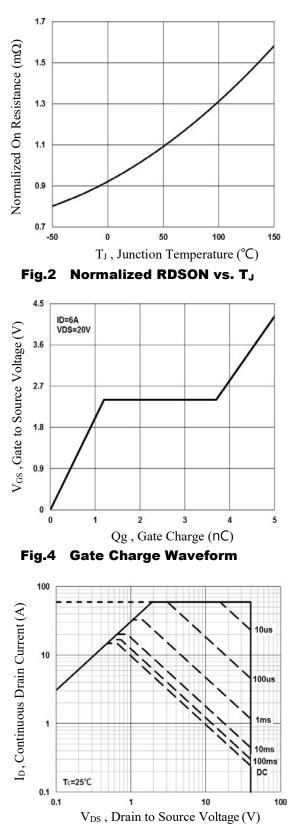


Fig.6 Maximum Safe Operation Area





P-CH Electrical Characteristics (TJ=25 °C, unless otherwise

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-40			V
$\Delta BV_{DSS}/\Delta T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C,I _D =-1mA		-0.04		V/°C
	Drain Sauras Laskana Cumant	V_{DS} =-40V , V_{GS} =0V , T_{J} =25°C			-1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =125°C			-10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±10V , V_{DS} =0V			±100	nA

On Characteristics

R _{DS(ON)} Static Drain-Source On-Resistance	Static Drain Source On Posiciance	V _{GS} =-10V , I _D =-5A		38	45	mΩ
	V_{GS} =-4.5V , I_D =-3A		45	70	mΩ	
V _{GS(th)}	Gate Threshold Voltage		-1.0	- 1.5	- 2.5	V
∆V _{GS(th)}	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-250uA		3		mV/°C
gfs	Forward Transconductance	V _{DS} =-10V , I _D =-3A		9		S

Dynamic and switching Characteristics

Qg	Total Gate Charge ^{2 , 3}		 9	
Q_gs	Gate-Source Charge ^{2 , 3}	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-5A	 2.5	nC
Q _{gd}	Gate-Drain Charge ^{2 , 3}		 3.2	
T _{d(on)}	Turn-On Delay Time ^{2 , 3}		 20	
Tr	Rise Time ^{2 , 3}	V_{DD} =-20V , V_{GS} =-4.5V , R_{G} =25 Ω	 12	20
T _{d(off)}	Turn-Off Delay Time ^{2 , 3}	I _D =-1A	 46	ns
T _f	Fall Time ^{2 , 3}		 6	
Ciss	Input Capacitance		 1050	
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , F=1MHz	 110	pF
C _{rss}	Reverse Transfer Capacitance		 80	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current	V _G =V _D =0V , Force Current			-12	А
I _{SM}	Pulsed Source Current	VG-VD-OV, FOICe Cullent			-24	А
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V

Note :

4. Repetitive Rating : Pulsed width limited by maximum junction temperature.

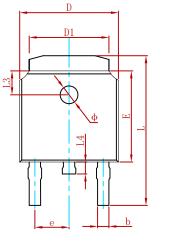
5. The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%.$

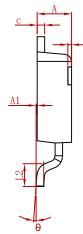
6. Essentially independent of operating temperature.



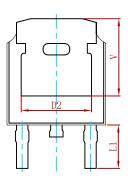


PACKAGE MECHANICAL DATA



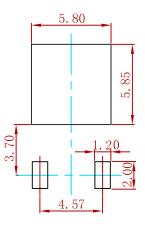


h



Symbol	Dimensions	In Millimeters	Dimension	s In Inches	
Symbol	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.635	0.770	0.025	0.030	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	REF.	0.190	REF.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.712	10.312	0.382	0.406	
L1	2.900	REF.	0.114	REF.	
L2	1.400	1.700	0.055	0.067	
L3	1.600	REF.	0.063	REF.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.250	REF.	0.207 REF.		

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

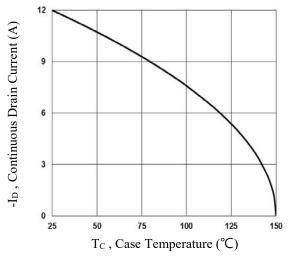
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

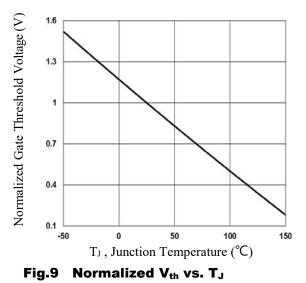
P/N PKG QTY			
	P/N	PKG	QTY
AOD609-MS TO-252-4 2500	AOD609-MS	TO-252-4	2500











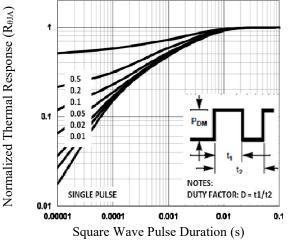


Fig.11 Normalized Transient Impedance

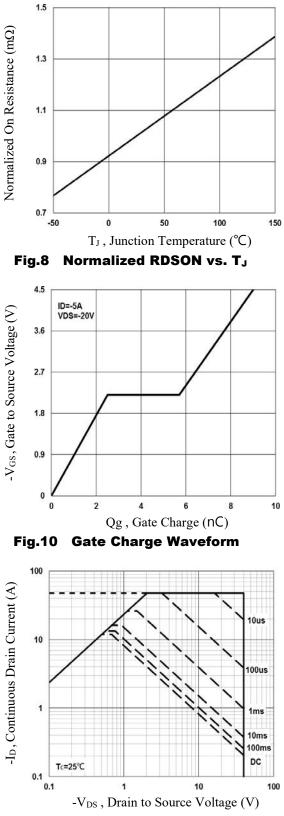


Fig.12 Maximum Safe Operation Area



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